

Vishay Siliconix

P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)		
- 20	0.039 at V _{GS} = - 4.5 V	- 4.7		
	0.052 at V _{GS} = - 2.5 V	- 4.1		
	0.068 at V _{GS} = - 1.8 V	- 3.5		

FEATURES

• TrenchFET[®] Power MOSFET

APPLICATIONS

- Load Switch
- PA Switch



COMPLIANT

Ordering Information: Si2323DS-T1 Si2323DS-T1-E3 (Lead (Pb)-free)

Parameter		Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 20		V	
Gate-Source Voltage		V _{GS}	± 8			
	T _A = 25 °C	– I _D	- 4.7	- 3.7	٨	
Continuous Drain Current (T _J = 150 °C) ^{a, b}	T _A = 70 °C		- 3.8	- 2.9		
Pulsed Drain Current		I _{DM}	- 20		A	
Continuous Source Current (Diode Conduction) ^{a, b}		I _S	- 1.0	- 0.6		
Maximum Power Dissipation ^{a, b}	T _A = 25 °C	- P _D	1.25	0.75	W	
	T _A = 70 °C		0.8	0.48		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	t ≤ 5 s	- R _{thJA} R _{thJF}	75	100	
Maximum Junction-to-Ambient ^a	Steady State		120	166	°C/W
Maximum Junction-to-Foot (Drain)	Steady State		40	50	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. Pulse width limited by maximum junction temperature.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

TO-236 (SOT-23) G 1 S 2 Top View Si2323DS (D3)* * Marking Code

Vishay Siliconix



	Symbol		Limits				
Parameter		Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = - 250 μ A	- 20			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	- 0.40		- 1.0	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -16 V, V_{GS} = 0 V$			- 1		
		V_{DS} = - 16 V, V_{GS} = 0 V, T_{J} = 55 °C	$T_{\rm GS} = 0 \text{ V}, \text{T}_{\rm J} = 55 ^{\circ}\text{C}$		- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \leq$ - 5 V, V_{GS} = - 4.5 V	- 20			А	
Drain-Source On-Resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_{D} = -4.7 \text{ A}$		0.031	0.039	1	
		$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -4.1 \text{ A}$	0.041 0.0		0.052	Ω	
		$V_{GS} = -1.8 \text{ V}, I_{D} = -2.0 \text{ A}$		0.054	0.068	1	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -5 V, I_{D} = -4.7 A$		16		S	
Diode Forward Voltage	V _{SD}	I _S = - 1.0 A, V _{GS} = 0 V		- 0.7	- 1.2	V	
Dynamic ^b	-1		1		1 1		
Total Gate Charge	Qg			12.5	19	nC	
Gate-Source Charge	Q _{gs}	V _{DS} = - 10 V, V _{GS} = - 4.5 V I _D ≅ - 4.7 A		1.7			
Gate-Drain Charge	Q _{gd}	D = -4.7 A		3.3			
Input Capacitance	C _{iss}			1020		pF	
Output Capacitance	C _{oss}	V_{DS} = - 10 V, V_{GS} = 0 V, f = 1 MHz		191			
Reverse Transfer Capacitance	C _{rss}			140			
Switching ^c	· ·						
Turn-On Time	t _{d(on)}			25	40	ns	
	t _r	$V_{DD} = -10 V, R_{L} = 10 \Omega$		43	65		
Turn-Off Time	t _{d(off)}	$I_D \cong$ - 1.0 A, V_{GEN} = - 4.5 V R _G = 6 Ω		71	110		
	t _f	16 - 0 32		48	75		

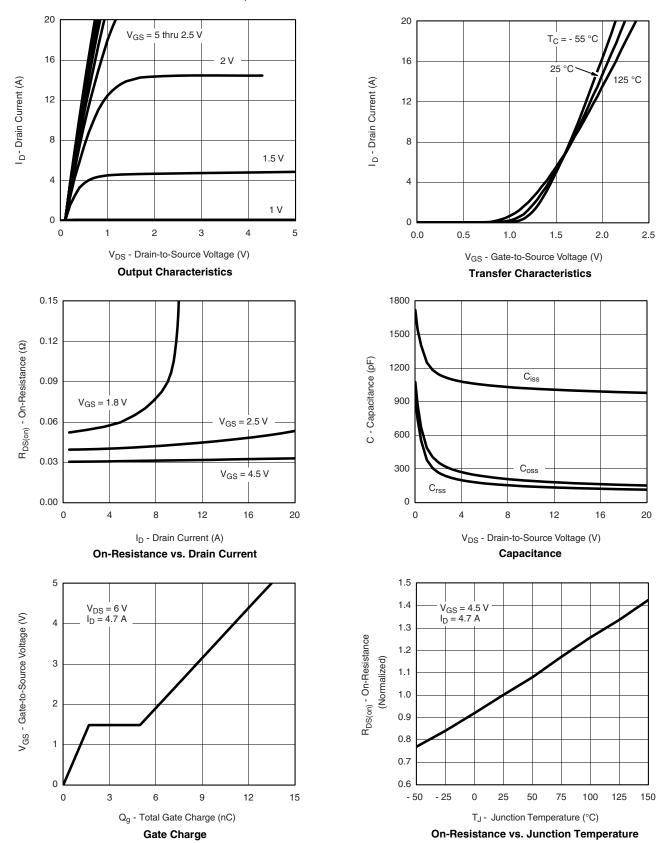
Notes:

a. Pulse test: PW \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. For DESIGN AID ONLY, not subject to production testing.

c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

VISHAY

Document Number: 72024 S-81954-Rev. C, 25-Aug-08 www.vishay.com 3

Si2323DS

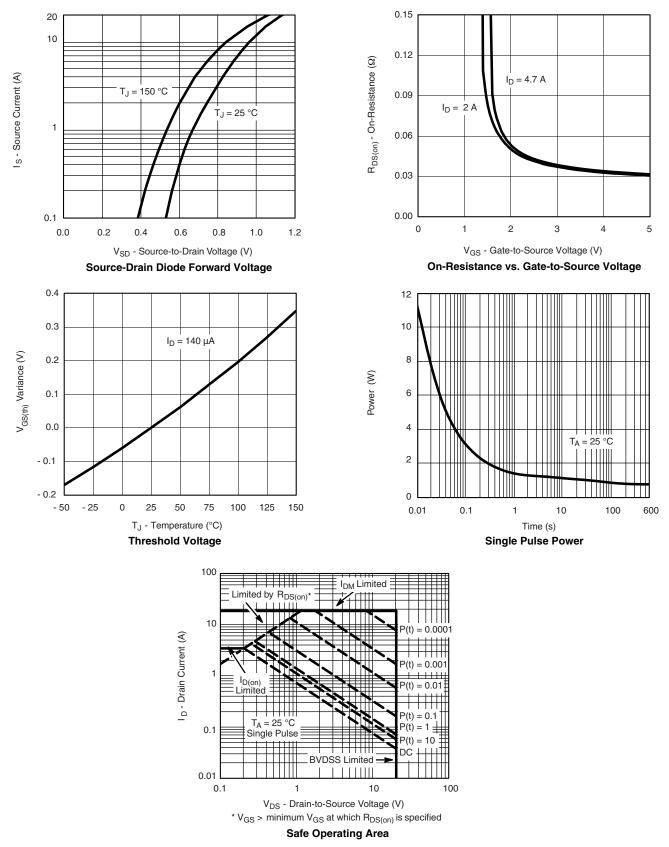
Vishay Siliconix

Si2323DS

Vishay Siliconix



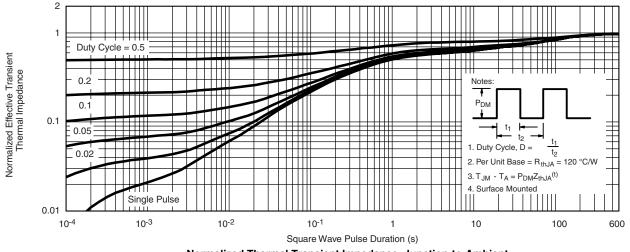
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Si2323DS Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72024.



Vishay

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.